Proposed 1st Ship Date: Dec. 13, 2019 Change Type: □ Design □ Wafer Bump Site □ Assembly Site □ Assembly Process □ Data Sheet □ Wafer Bump Material □ Wafer Bump Material □ Assembly Materials □ Part number change □ Wafer Bump Process □ Wafer Fab Site □ Packing/Shipping/Labeling □ Test Process □ Wafer Fab Materials □ Wafer Fab Process Notification Details Description of Change: Texas Instruments Incorporated is announcing a change. The product datasheet(s) is being updated as summarized below. TPS63050, TPS630 SLYSAMED - JULY 2013 - REVISED AUGUST 2	PCN Number:	20190829000.1 PCN Date: Sept. 13, 2019									
Customer Contact: PCN Manager Dept: Quality Service	Title: Datasheet for	TPS63050, TPS63051									
Change Type: Assembly Site Assembly Process Assembly Materials Assembly Materials Part number change Mechanical Specification Test Site Packing/Shipping/Labeling Test Process Notification Details Description of Change: Texas Instruments Incorporated is announcing a change. The product datasheet(s) is being updated as summarized below. Texas Instruments Incorporated is announcing a change. The product datasheet(s) is being updated as summarized below. Texas Instruments Texas Instruments Incorporated is announcing a change. The product datasheet(s) is being updated as summarized below. Texas Instruments Texas Instruments Texas Instruments Incorporated is announcing a change. The product datasheet(s) is being updated as summarized below. Texas Instruments Texas Instruments Incorporated is announcing a change. The product datasheet(s) is being updated as summarized below. Texas Instruments Incorporated is announcing a change. The product datasheet(s) is being updated as summarized below. Texas Instruments Incorporated is announcing a change. The product Materials Texas Instruments Incorporated is announcing a change. Texas Instruments Incorporated is announcing a change. Texas Instruments Incorporated is announcing a change. Texas Instruments Incorporated is announcing a change. Texas Instruments Incorporated is announcing a change. Texas Instruments Incorporated is announcing a change. Texas Instruments Incorporated is announcing a change. Texas Instruments Incorporated is announcing a change. Texas Instruments Incorporated is announcing a change. Texas Instruments Incorporated is announcing a change. Texas Instruments Incorporated is announcing a change. Texas Instruments Incorporated is announcing a change. Texas Instruments Incorporated is announcing a change. Texas Instruments Incorporated is announcing a change. Texas Instruments Incorporated is announcing a change. Texas Instruments Incorporated is announcing a change. Texas Instruments Incorporated is announcing a cha	Customer Contact: PCN Manager						Dept:		Quality Services		
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